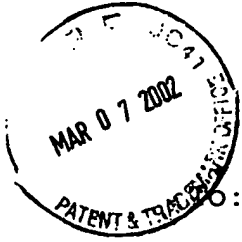


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To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/017,955 12/14/01

Harry Chuang

LOCALIZED SLOTS FOR STRESS RELIEVE  
IN COPPER

Grp. Art Unit: 2812

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner of Patents and  
Trademarks, Washington, D.C. 20231, on February 27, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B Ackerman 2/27/02

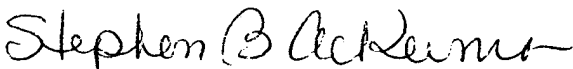
U.S. Patent 6,146,025 to Abbink et al., "Laser Diode and Substrate," discloses a method of applying a laser diode and substrate.

U.S. Patent 6,140,700 to Shin, "Semiconductor Chip Package and Method for Fabricating the Same," discloses a semiconductor chip package and a method of creating this package.

U.S. Patent 5,920,118 to Kong, "Chip-Size Package Semiconductor," discloses a chip-size semiconductor package.

U.S. Patent 6,258,715 to Yu et al., "Process for Low-K Dielectric with Dummy Plugs," discloses a process to form dummy plugs to relieve stress.

Sincerely,

  
Stephen B. Ackerman,  
Reg. No. 37761